Material Declaration Report

PERICOM® Semiconductor Corporation
www.pericom.com

Package Type:	TSSOP 48L (6.1mm)
Pericom Package Code:	A48(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	190.996
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10~20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	12/2/2008

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
			Silica Fused	60676-86-0	89.800	116.7344
MOLD COMPOUND	129.994	OSE	Epoxy Resin	Proprietary	5.000	6.4997
			Phenolic Resin	Proprietary	4.000	5.1998
			Others	Proprietary	1.000	1.2999
			Carbon Black	1333-86-4	0.200	0.2600
			Silica Fused	60676-86-0	88.000	114.3945
		SPEL	Epoxy Resin	Proprietary	5.000	6.4997
			Phenolic Resin	Proprietary	4.500	5.8497
			Epoxy, Cresol Novolac	29690-82-2	2.000	2.5999
			Carbon Black	1333-86-4	0.500	0.6500
			Copper (Cu)	7440-50-8	94.900	51.1829
LEADFRAME	53.934		Nickel (Ni)	7440-02-0	3.200	1.7259
			Silicon (Si)	7440-21-3	0.720	0.3883
			Magnesium (Mg)	7439-95-4	0.180	0.0971
			Silver(Ag)	7440-22-4	1.000	0.5393
SILICON DIE	2.300		Silicon (Si)	7440-21-3	99.192	2.2810
			Non-hazardous Metal	Proprietary	0.808	0.0186
			Silver	7440-22-4	76.000	0.2308
DIE ATTACH EPOXY	0.304	OSE	Acrylic Resin	Proprietary	8.000	0.0243
			Acrylate	Proprietary	5.500	0.0167
			Polybutadiene derivative	Proprietary	5.500	0.0167
			Epoxy resin	Proprietary	2.500	0.0076
			Additive	Proprietary	1.000	0.0030
			Butadiene copolymer	Proprietary	1.000	0.0030
			Peroxide	Proprietary	0.500	0.0015
			Silver	7440-22-4	80.000	0.2430
		SPEL	Epoxy Resin	9003-36-5	10.000	0.0304
			Diluent	26447-14-3	6.000	0.0182
			Hardener	620-92-8	3.250	0.0099
			Dicyandamide	461-58-5	0.750	0.0023
GOLD WIRE	0.728		Gold(Au)	7440-57-5	99.990	0.7276
			Impurities	-	0.010	0.0001
SOLDER PLATING	3.738		Tin (Sn)	7440-31-5	99.990	3.7374
			Impurities	-	0.010	0.0004

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

	MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
	Mold Compound	<2	<2	<2	<2	<5	<5
	Leadframe	<50	<2	<2	<2	<5	<5
Device	Silicon Die	<2	<2	<2	<2	<5	<5
	Die Attach Epoxy	<2	<2	<2	<2	<5	<5
	Gold Wire	<2	<2	<2	<2	<5	<5
	Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC

and

China RoHS Directive SJ/T11363-2006

Declaration Statement: Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium

Pb <1000ppm	Hg <1000ppm	Cr+6 <1000ppm	Cd <100ppm	PBB <1000ppm	PBDE <1000ppm
O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.